Messrs. Digi-Key

 Issue No.
 : PC-02-064

 Date of issue : November 15, 2002

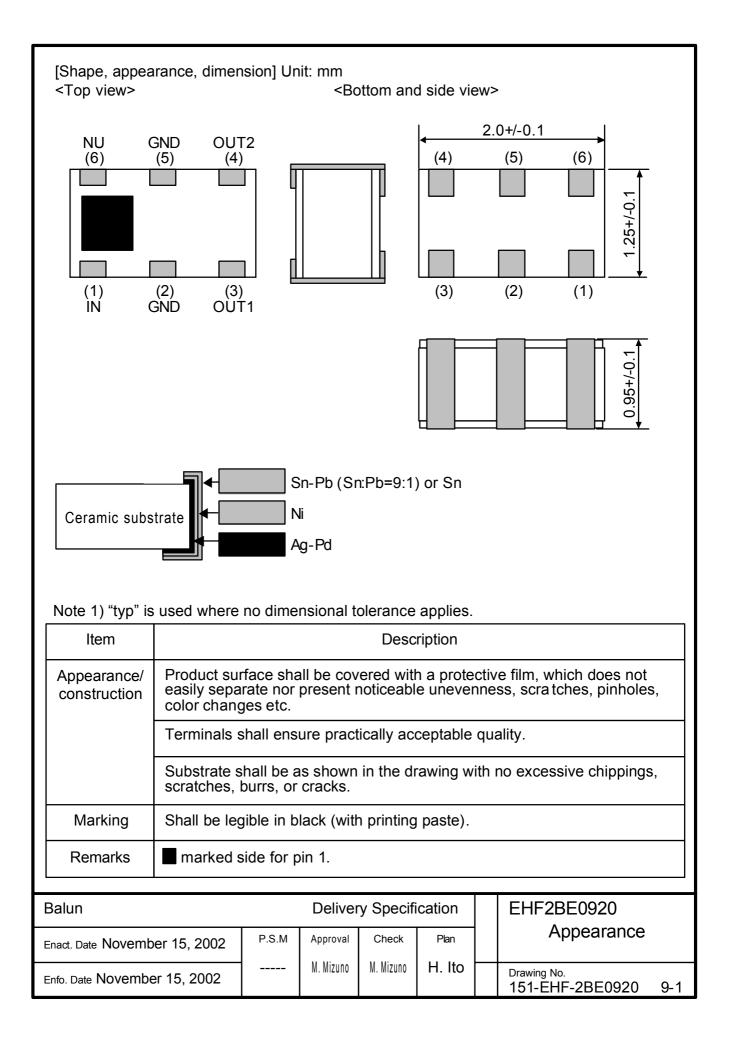
 Classification : ■ New□Change□ Renewal

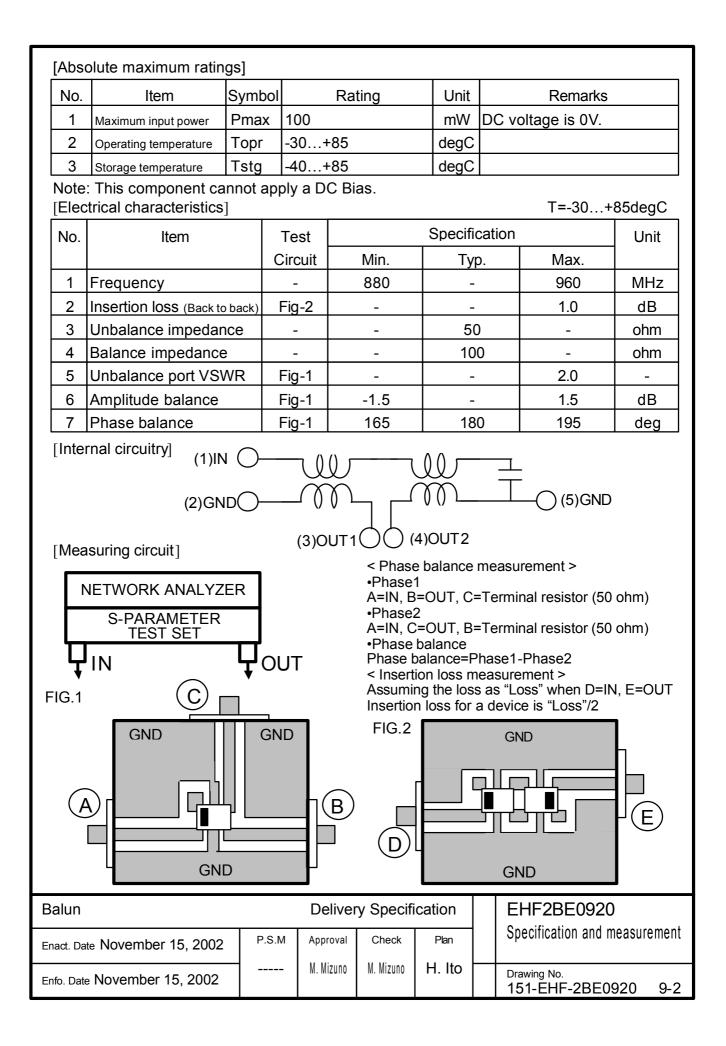
Delivery Specification

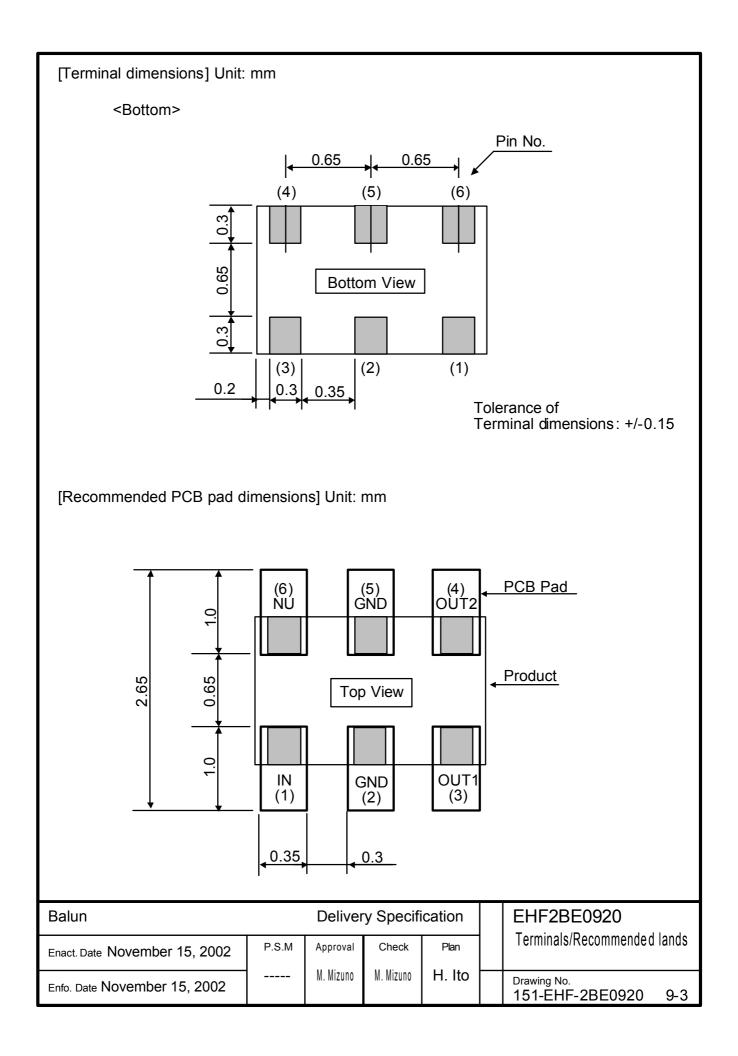
Product Description	: Balun
Product Part Number	: EHF2BE0920
Classification of Spec	: Individual Product Specification
Applications	: Cellular phone
	For other applications, contact the undersigned in advance.
Term of Validity	: November 14, 2007 from the date of issue.

CUSTOMER USE ONLY	Receipt Record#:
This was certainly received by us. 1(one) copy is being returned to you.	Date of receipt:
	Received by:
	Title: Dept.:

Matsushita Electronic Components Co., Ltd.		
Network Device Company	Prepared by	: H. Ito
Module Strategic Business Unit	Checked by	: M. Mizuno
Engineering Group HFD Team		
992-1 Aiba Ohno-cho Ibi-gun Gifu 501-0598 JAPAN	Authorized by	: M. Mizuno
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[Quality characteristic	ş]						
Test item	Test condition	Judgment criteria					
High temperature	+85degC, 1000h	No abnormality shall be observed in					
Low temperature	-40degC, 1000h	appearance or					
High-temperature high-humidity storage	+60degC, 90%RH, 1000h	electrical characteristics.					
Pressure Pot	+121degC, 99%RH, 2.026x10 ⁵ Pa, 100h	characteristics.					
Temperature cycling	-40…+85degC, Each 30 min., 200cy						
Vibration	10500Hz, 10G, in each direction of XYZ, 2h30min.						
Impact	100G, 6mS, Half sinusoidal wave, in each direction of XYZ, 3 times						
Shock (Drop)	1.8m, 6 facesx6cy(36 times with 100g Dummy Load)						
Electro static discharge	200pF, 0 ohm, +/-200V, Each 5 times						
Soldering heat resistance	Manual hot gas: 260+/-10degC, 30 sec., 2 times	Over 90% of the terminal					
	Soldering iron: 260+/-10degC, 3 sec., 2 times	surface shall be covered with solder.					
	Reflow: 260degC peak, 2 times						
Solder ability	Solder bath: 235+/-5degC, 2 sec.	Over 95% of the terminal					
	Reflow: 230degC	surface shall be covered with solder.					
Board warping	Assemble this component on a PC board with 0.8mm thickness using the recommended soldering condition shown below, and apply a bending force of 3mm warping at a rate of 1mm/sec. 5 seconds and 5 times. t=0.8mm						
Terminal removal	Solder a component on a PC board using the recommended of then press the component sideways at 1mm/sec. Destruction lir						
Seating plane co-planarity	Within 0.1mm						
< Recommended sold Diagram1 Shown b degC 250 230 230 170 140	below is a recommended reflow soldering condition						
↓	30~60 sec. 60~180 sec.	<u>↓ Time</u>					
Balun Delivery Specification EHF2BE0920							
Enact. Date November 15, 2002 P.S.M Approval Check Plan Quality Chara							
Enfo. Date November 15, 20	^{g No.} EHF-2BE0920 9-4						

[Cautions for use]

- (1) Operating a product over the maximum rating for even a moment may result in a product failure or breakage. Never use a product in such a condition that it may cause a safety problem.
- (2) Opening or short-circuiting the product terminals or inserting a product in the reverse orientation while power is being supplied may cause a breakage. Always avoid such circumstances.
- (3) Operations in a corrosive gas atmosphere or improper environments such as high-temperature, high-humidity or dewy conditions may lead to product performance deterioration, a breakage, a change in appearance etc. Please avoid such conditions, as they are unsafe.
- (4) Always ground the soldering iron or soldering bath used for assembly operation to avoid any excessive voltage applied to a product.
- (5) After soldering with solder bridges, incomplete soldering or in the reverse orientation, supplying power may result in a product breakage. Please confirm the soldered condition before supplying power to the product.
- (6) Excessive stress on the terminals may cause a contact failure or performance deterioration. Please use caution.
- (7) Please provide a fail-safe provision in the product you design by taking any failure of our product into consideration.
- (8) This product does not include a DC-cutting device. Application of a DC voltage between the Balance port and the Unbalance port may cause product deterioration or breakage.
 - * If any question arises about the safety of this product, please contact us immediately with a request for an engineering examination.

[Remarks]

- *1: All of the materials used in this product are those listed as the existing chemical substances based on the "Law for examination and regulation of manufacture of chemical substances".
- *2: The production process of this product does not use any ozone-depleting chemicals (OZC) regulated by the Montreal Protocol.
- *3: Validity of this specification is 5 years from the date of issue, but the validity is considered on going unless any changes are made.

Balun		Delivery Specification				EHF2BE0920		
Enact. Date November 15, 2002	P.S.M	Approval	Check	Plan		Cautions		
Enfo. Date November 15, 2002		M. Mizuno	M. Mizuno	H. Ito		Drawing No. 151-EHF-2BE0920 9-5		

[Packaging materials] 1. Materials

- 1) Embossed carrier tape (Refer to the attachment)
- 2) Top tape: Anti-static
- 3) Packaging box (Refer to the attachment)4) Packaging tape, carrier-securing adhesive tape
- 2. Specification

	·							
No.	Item			Remarks				
1	Reel outer diameter	Refer	to the att					
2	Reel inner diameter	Refer	to the att					
3	Reel inner width	Refer	to the att	achment				
4	Quantity in a reel	4000 p	<u>pieces/re</u>	el				
5	Taping direction						ling direction ngs facing up)	
6	Top tape attachment position	Top tape	pe attachm			5.5mm Emb	tape	Tape breaks force. Min. 10N Top cover tape strength. Min. 10N Tape peel force. 0.11.0N Tape peel angle. 165180degree Reel weight. Max 1500g
7	Label attachment position	Tape unreeling direction						Indicated Item Pat No., Lot No. Quantity, Maker Country of Origin
8	Tape leader part and tape ending part	20	part Prod		f)0~150mm, 2	Leader	Top tape	
9	9 Missing products No missing products shall be allowed.							
10Packaged quantity in a box21 reels/box (Max)84000 pieces/box(Max)								
					BE0920 ging specification 1			
Enfo Data November 15, 2002 M. Mizuno M. Mizuno H. Ito Drawing M					No. HF-2BE0920 9-6			



- 1) Load products in each cavity of an embossed carrier tape, in the correct orientation, by leaving the product-unloaded part shown in Item No. 8(P9-6) of the packaging specification.
- 2) Heat-seal a top tape in good alignment on the carrier tape.
- 3) After 4000 pieces are loaded and reeled, provide a product-unloaded part at the tape-leader portion. Secure the tip of the carrier tape with a piece of adhesive tape.
- 4) Stack the reels (21 reels max.) and enclose them in a packaging box. Close the flaps with a piece of adhesive tape.
- 5) Provide markings on the packaging box.
 - < Items to be indicated >
 - 1. Part No.
 - 2. Quantity
 - 3. Lot No.
 - 4. Manufacturer name
 - 5. Country of origin

